

## ABSTRACT

A circuit board adapted to a fan comprises a circuit region and a heat-dissipative film. The circuit region is provided on a first surface of the circuit board and comprises at least one heat-generating component thereon. The heat-dissipative film is coated on  
5 an edge portion of the first surface and is in contact with the heat-generating component. A plurality of openings through the heat-dissipative film, a protrusion of the circuit board, a cutout in the protrusion to expose the heat-generating component to airflow, etc., have been disclosed and claimed for enhancing the efficiency in heat dissipation. A heat sink may also be provided on a second surface opposite to the first surface of the  
10 circuit board. The heat sink is connected to the heat-dissipative film to help dissipate the heat generated by the operation of the fan.